

Supplemental Preliminary Amendment

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Title: SUPPORT WITH SOLDER BALL ELEMENTS AND A METHOD FOR POPULATING
SUBSTRATES WITH SOLDER BALLS

IN THE ABSTRACT

Please replace the Abstract with the following newly written Abstract:

**SUPPORT WITH SOLDER BALL ELEMENTS AND METHOD FOR LOADING
SUBSTRATES WITH BALL CONTACTS**

Abstract

~~The invention relates to a~~ support (4) with solder ball elements (1) for loading substrates (2) with ball contacts is disclosed. ~~Furthermore~~ One embodiment, the ~~invention relates to~~ provides a system for loading substrates (2) with ball contacts and to a method for loading substrates (2) with ball contacts. ~~For this purpose,~~ The support (4) has a layer of adhesive (5) applied on one side, the layer of adhesive (5) losing its adhesive force to the greatest extent when irradiated. ~~Furthermore,~~ The support (4) has solder ball elements (1), which are arranged closely packed in rows (6) and columns (7) on the layer of adhesive (5) in a prescribed pitch (w) for a semiconductor chip or a semiconductor component.

~~{figure 1}~~